

## AMENDMENTS TO THE CLAIMS

Please amend the Claims as follows and without prejudice. This listing of Claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-9 (Cancelled)

10. (New) A method for manufacturing semiconductor granules intended to feed a semiconductor material manufacturing melt, said method comprising a step of sintering by compacting and thermal processing of powders of at least one material belonging to the group formed by silicon, germanium, gallium arsenide, and the alloys thereof.

11. (New) The method of claim 10, wherein the granules have a size greater than 1 mm.

12. (New) The method of claim 10, wherein the powders comprise powders of nanometric and/or micrometric size.

13. (New) The method of claim 10, further comprising a compaction step followed with a thermal processing step.

14. (New) The method of claim 13, wherein the pressure ranges between 10 MPa and 1 GPa and the temperature is greater than 800°C.

15. (New) The method of claim 10, further comprising a hot pressing step.

16. (New) The method of claim 15, wherein, in the hot pressing step, the pressure is lower than 100 MPa and the temperature is greater than 800°C.

17. (New) The method of claim 10, further comprising a step of placing the powders in a mould.

18. (New) The method of claim 10, wherein the powders are doped semiconductor powders.

19. (New) The method of claim 10, further comprising a step of annealing or doping of the granules.